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Damboulev et al.

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(54) **PAIR OF HEADPHONES**

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(**) Term: **15 Years**

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(51) **LOC (11) Cl.** **14-01**

(52) **U.S. Cl.**
USPC **D14/205**; D14/226

(58) **Field of Classification Search**
USPC D14/205, 188, 192, 224, 225–228; D29/112; 2/209; 181/129, 130, 135;
(Continued)

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Design U.S. Appl. No. 29/569,403, filed Jun. 27, 2016 (which is owned by the owner of this Application), and its ongoing prosecution history, including without limitation Office Actions, Amendments, Remarks, prior art references, and any other potentially relevant documents or statements.

Primary Examiner — Paula Allen Greene

(74) *Attorney, Agent, or Firm* — Proven Patents Law Firm; Kregg A. Koch

(57) CLAIM

An ornamental design for a pair of headphones, as shown and described.

DESCRIPTION

FIG. **1** is a first perspective view of an embodiment of a pair of headphones.

FIG. **2** is a second perspective view of the embodiment of the pair of headphones shown in FIG. **1**.

FIG. **3** is a top view of the embodiment of the pair of headphones shown in FIG. **1**.

FIG. **4** is a bottom view of the embodiment of the pair of headphones shown in FIG. **1**.

FIG. **5** is a first side view of the embodiment of the pair of headphones shown in FIG. **1**.

FIG. **6** is a second side view of the embodiment of the pair of headphones shown in FIG. **1**, the second side being generally opposite to the first side shown in FIG. **5**.

FIG. **7** is a front view of the embodiment of the pair of headphones shown in FIG. **1**.

FIG. **8** is a back view of the embodiment of the pair of headphones shown in FIG. **1**.

FIG. **9** is an enlarged, perspective view of a first earpiece portion of the embodiment of the pair of headphones shown in FIG. **1**.

FIG. **10** is an enlarged, top view of the first earpiece portion of the embodiment of the pair of headphones shown in FIG. **1**.

FIG. **11** is an enlarged, bottom view of the first earpiece portion of the embodiment of the pair of headphones shown in FIG. **1**.

FIG. **12** is an enlarged, side view of the first earpiece portion of the embodiment of the pair of headphones shown in FIG. **1**, showing an outside surface of the first earpiece portion.

FIG. **13** is an enlarged, side view of the first earpiece portion of the embodiment of the pair of headphones shown in FIG. **1**, showing an inside surface of the first earpiece portion.

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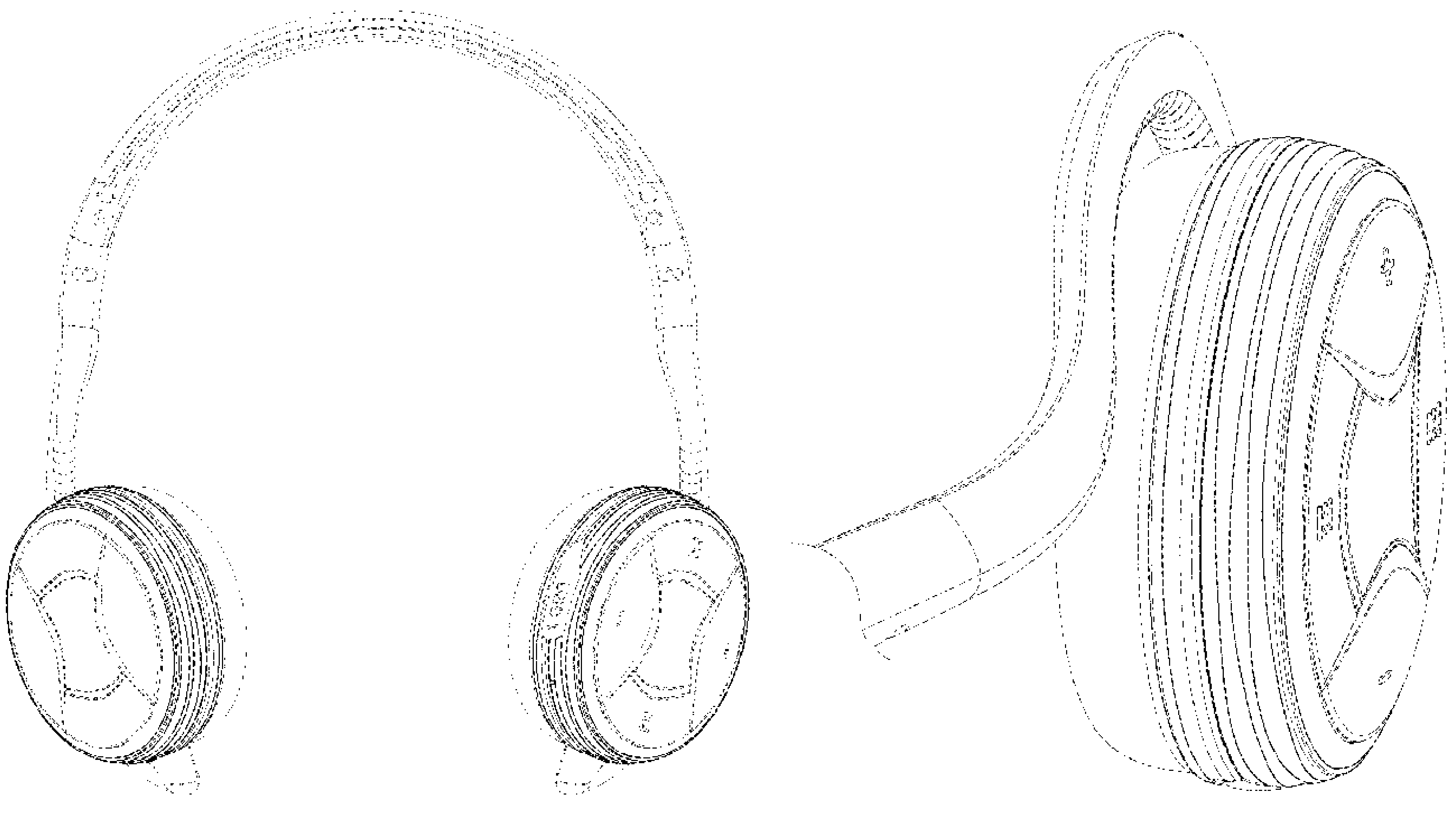

FIG. **14** is an enlarged, front view of the first earpiece portion of the embodiment of the pair of headphones shown in FIG. **1**.
FIG. **15** is an enlarged, back view of the first earpiece portion of the embodiment of the pair of headphones shown in FIG. **1**.
FIG. **16** is an enlarged, perspective view of a second earpiece portion of the embodiment of the pair of headphones shown in FIG. **1**.
FIG. **17** is an enlarged, top view of the second earpiece portion of the embodiment of the pair of headphones shown in FIG. **1**.
FIG. **18** is an enlarged, bottom view of the second earpiece portion of the embodiment of the pair of headphones shown in FIG. **1**.
FIG. **19** is an enlarged, side view of the second earpiece portion of the embodiment of the pair of headphones shown in FIG. **1**, showing an outside surface of the second earpiece portion.
FIG. **20** is an enlarged, side view of the second earpiece portion of the embodiment of the pair of headphones shown in FIG. **1**, showing an inside surface of the second earpiece portion.
FIG. **21** is an enlarged, front view of the second earpiece portion of the embodiment of the pair of headphones shown in FIG. **1**; and,
FIG. **22** is an enlarged, back view of the second earpiece portion of the embodiment of the pair of headphones shown in FIG. **1**.
The broken lines depict environmental structure and form no part of the claimed design.

1 Claim, 20 Drawing Sheets

(58) **Field of Classification Search**
USPC 379/430, 431; 381/380, 381, 74, 375, 381/379, 384, 370, 151; 455/90.3, 575.1, 455/569.1; D9/430, 431; D28/78
CPC H04R 1/1066; H04R 1/1016; H04R 1/10; H04R 25/00; H04R 1/1033; H04R 1/02; H04R 9/06; H04R 5/00
See application file for complete search history.

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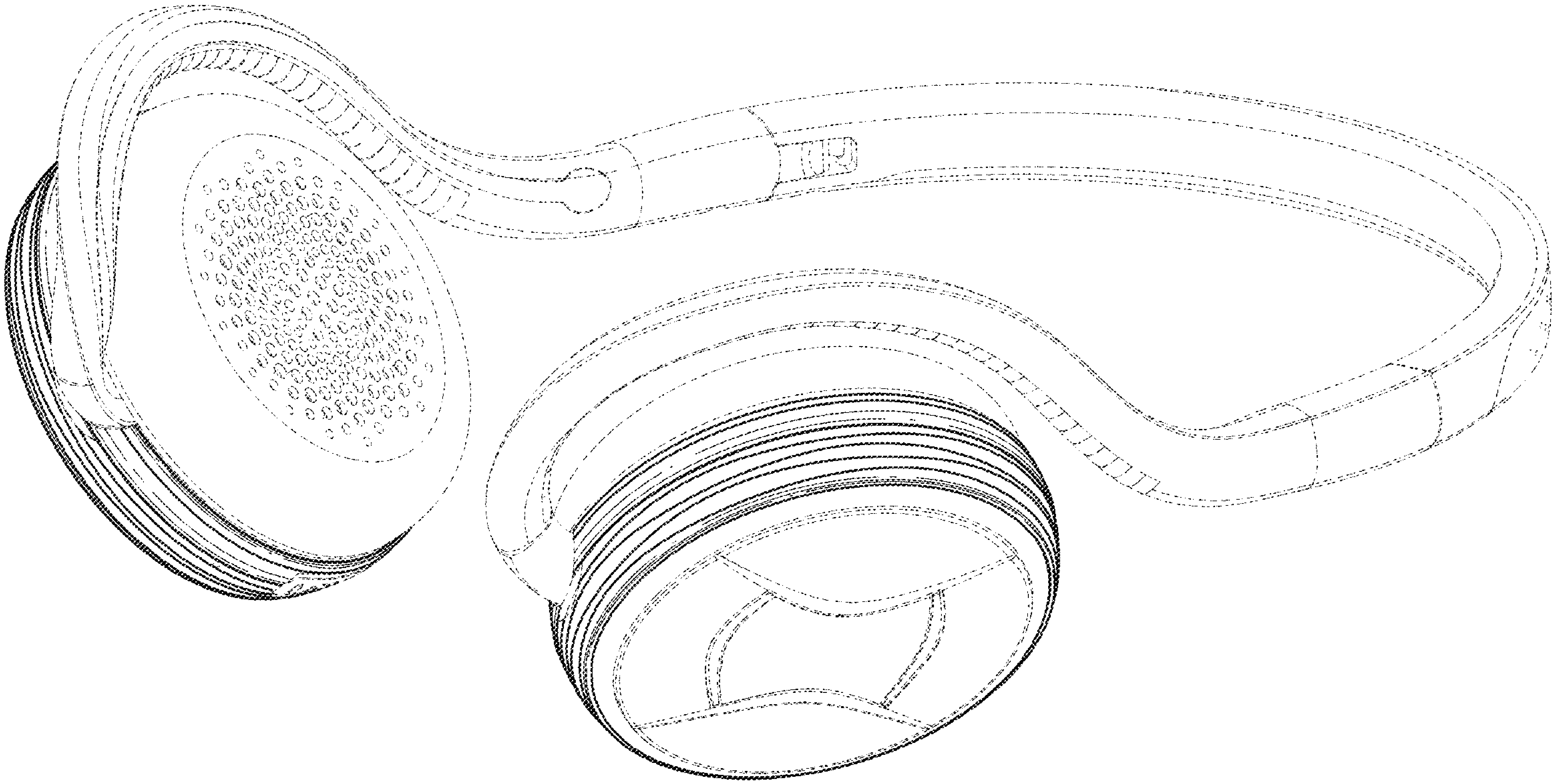


FIG. 1

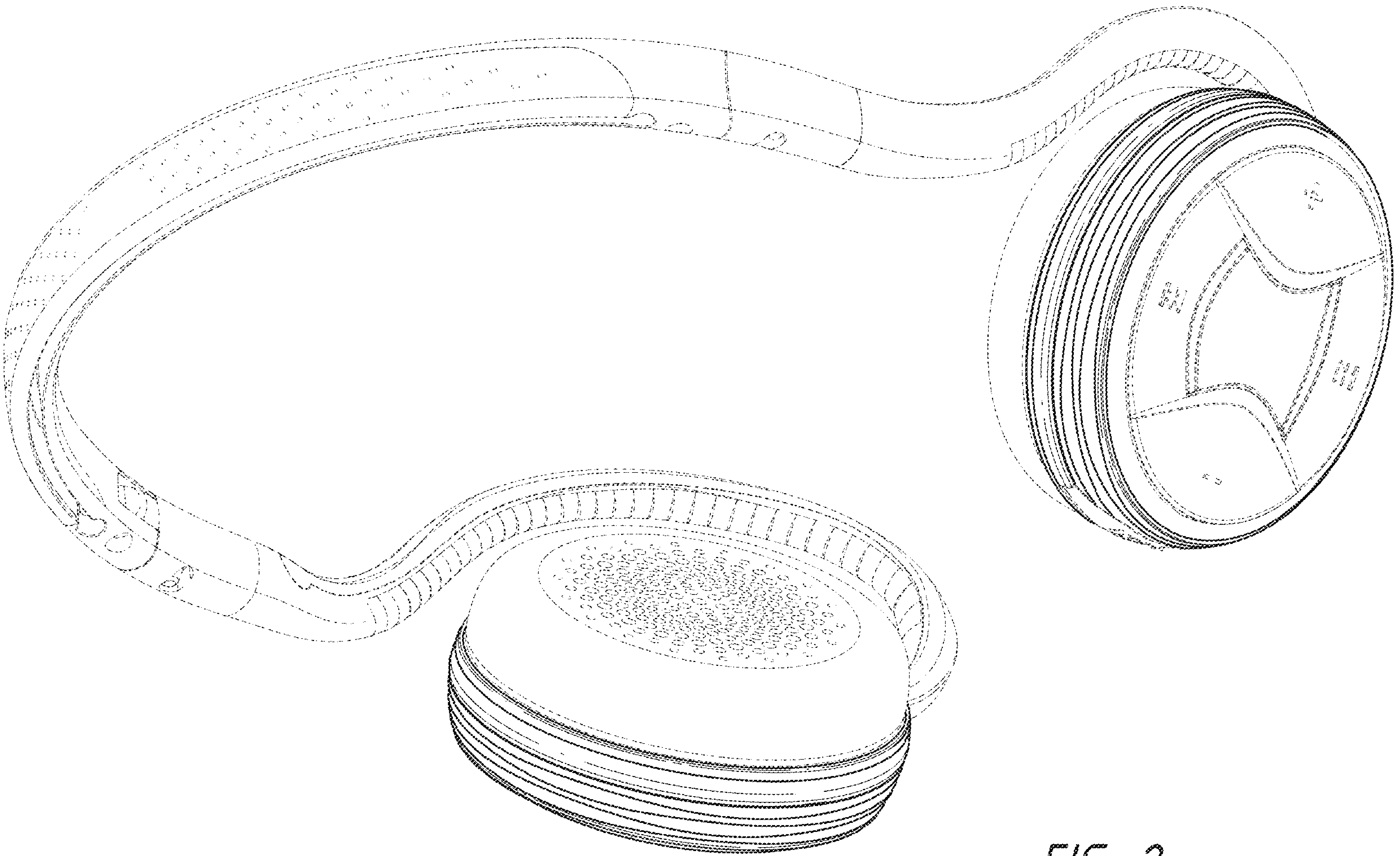
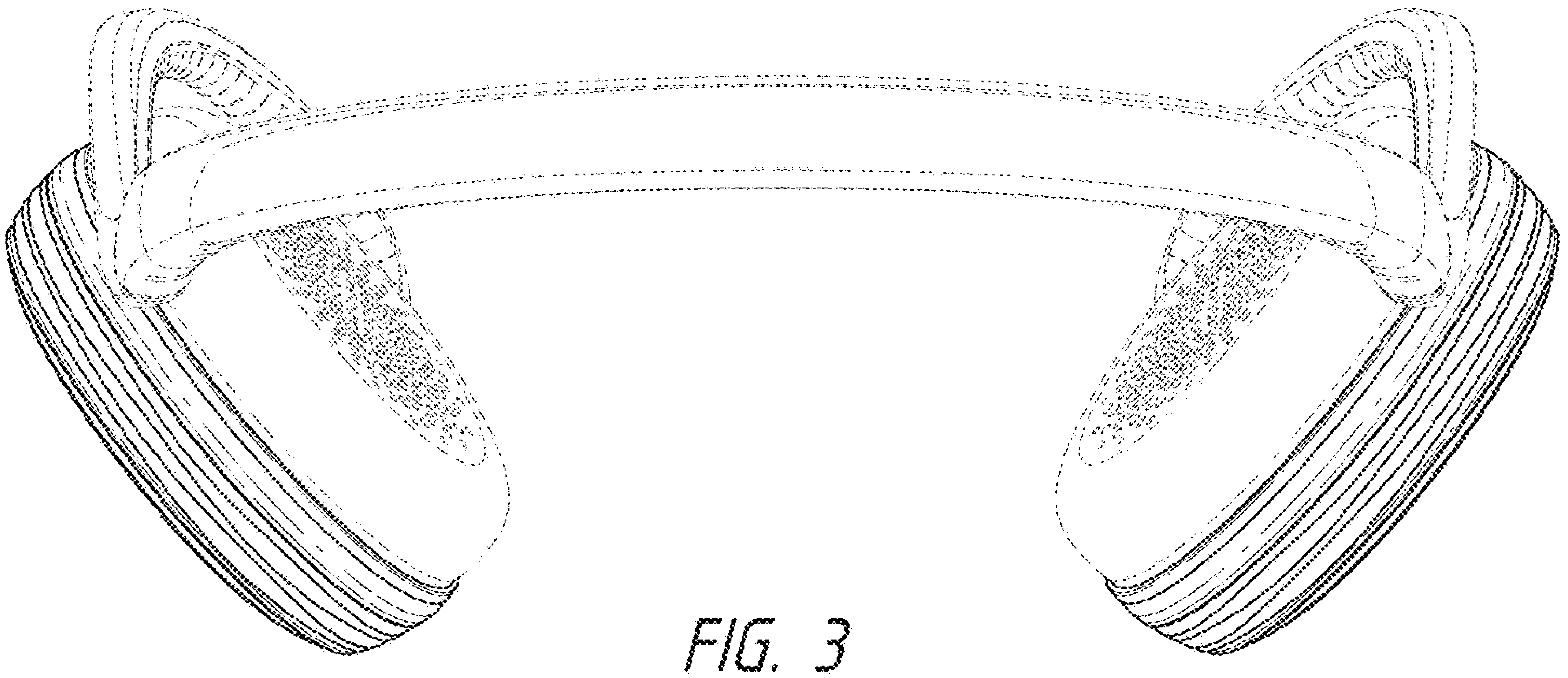


FIG. 2



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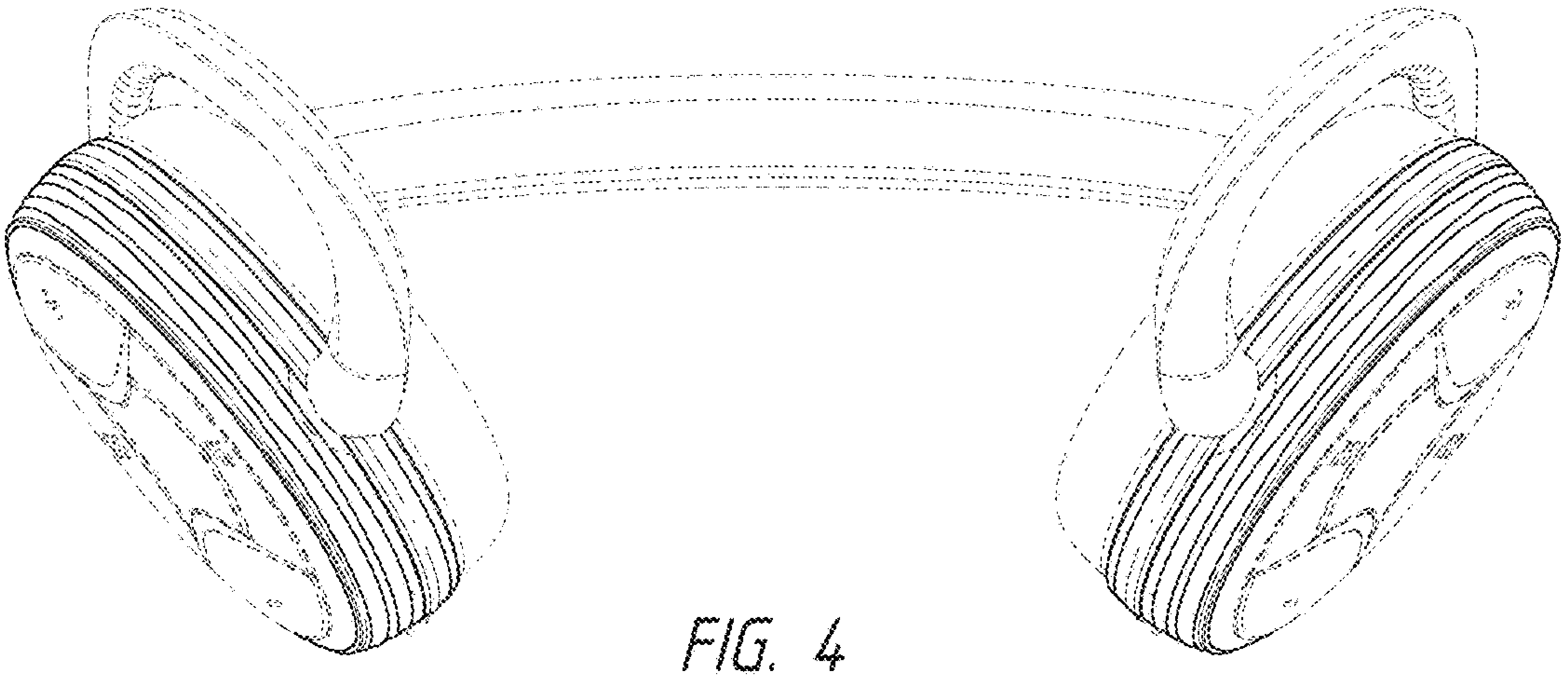


FIG. 4

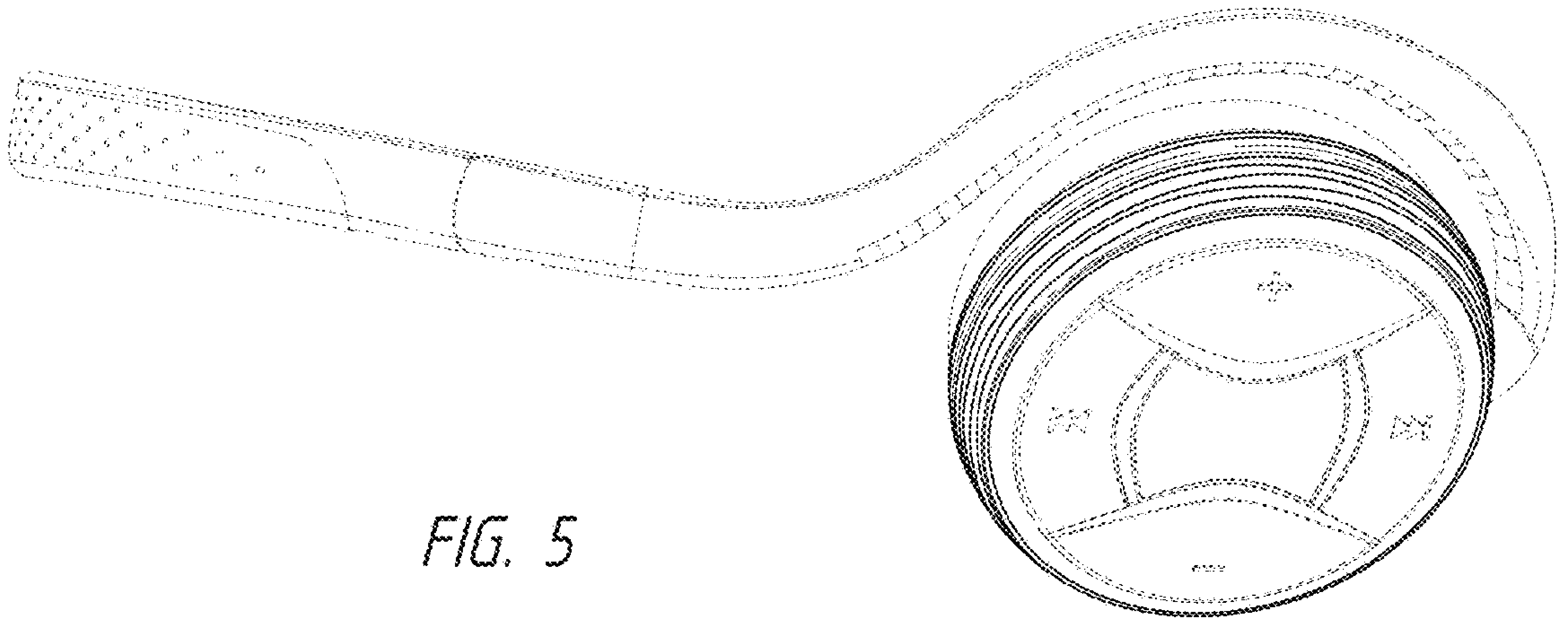


FIG. 5

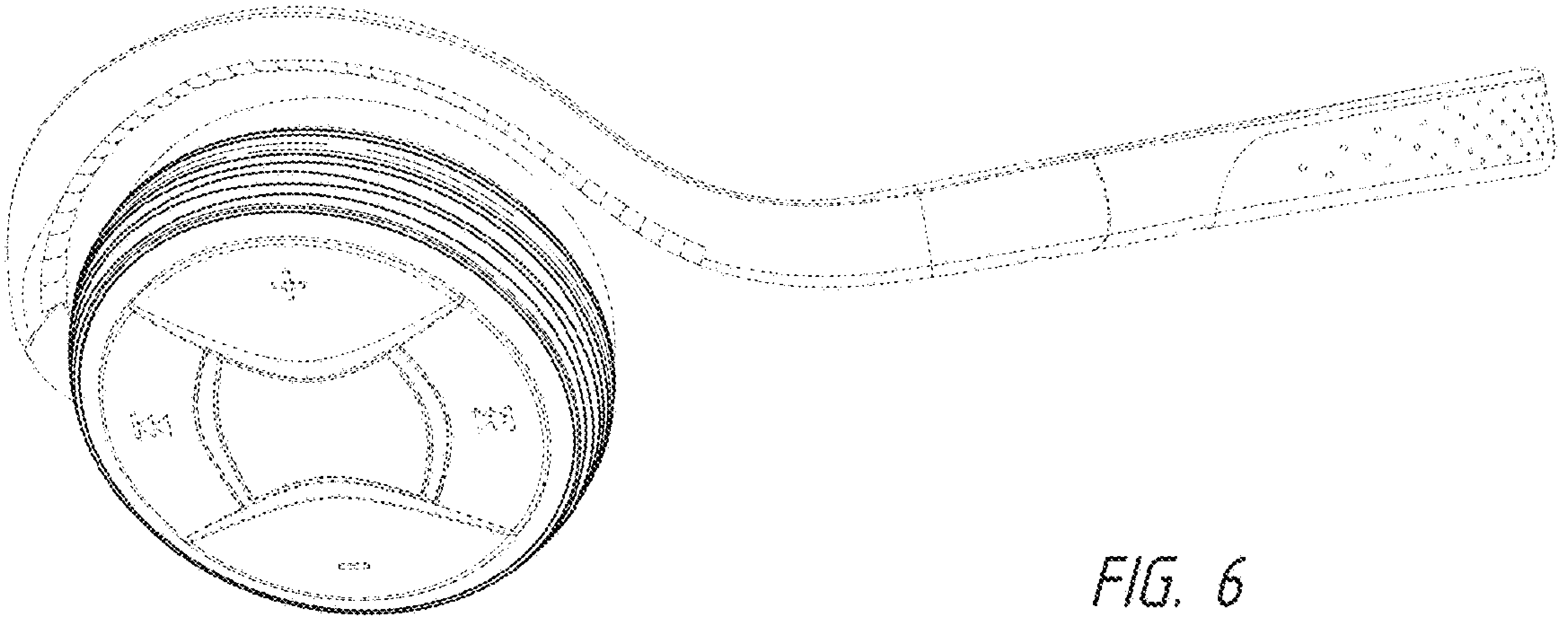


FIG. 6

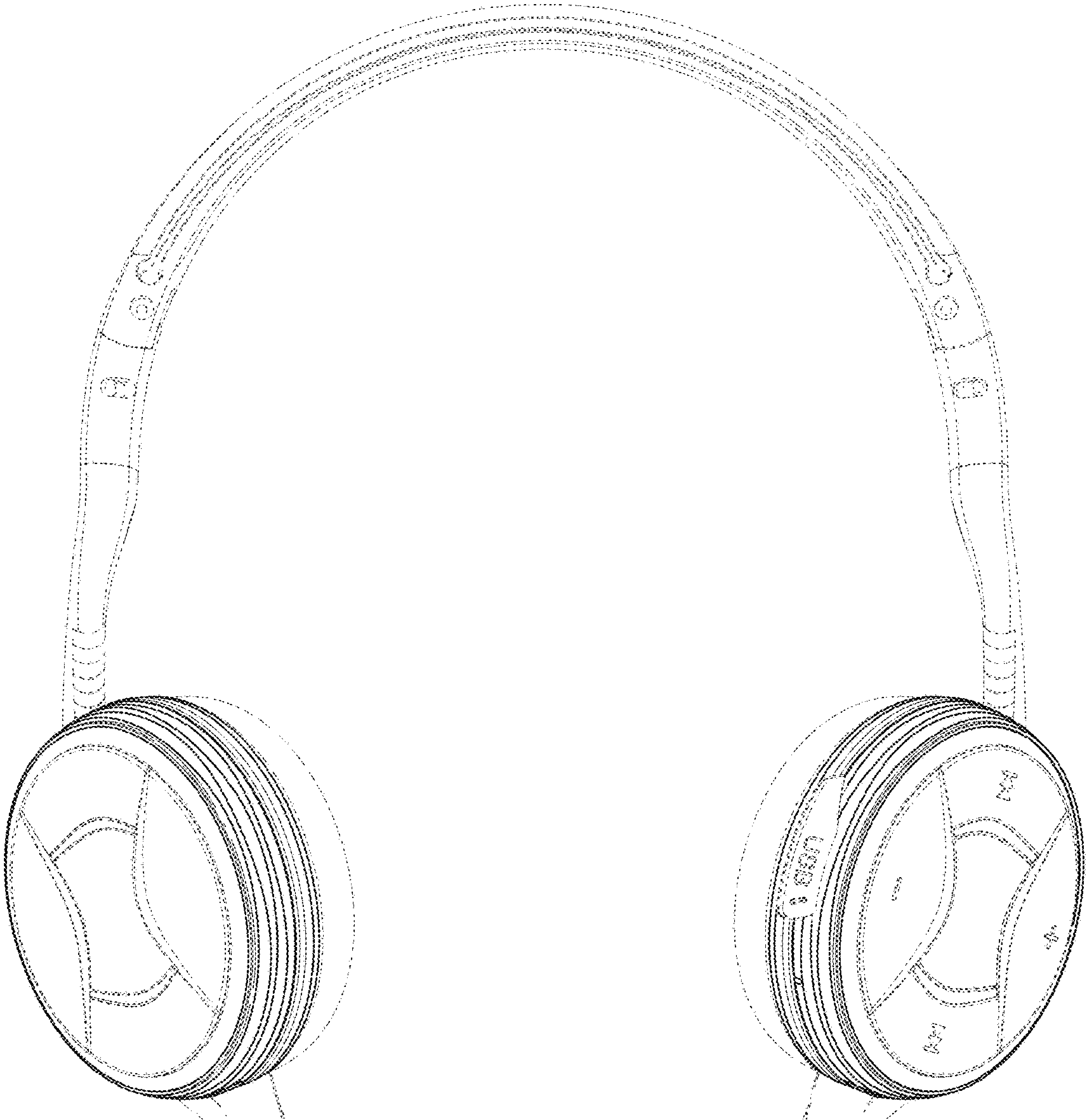
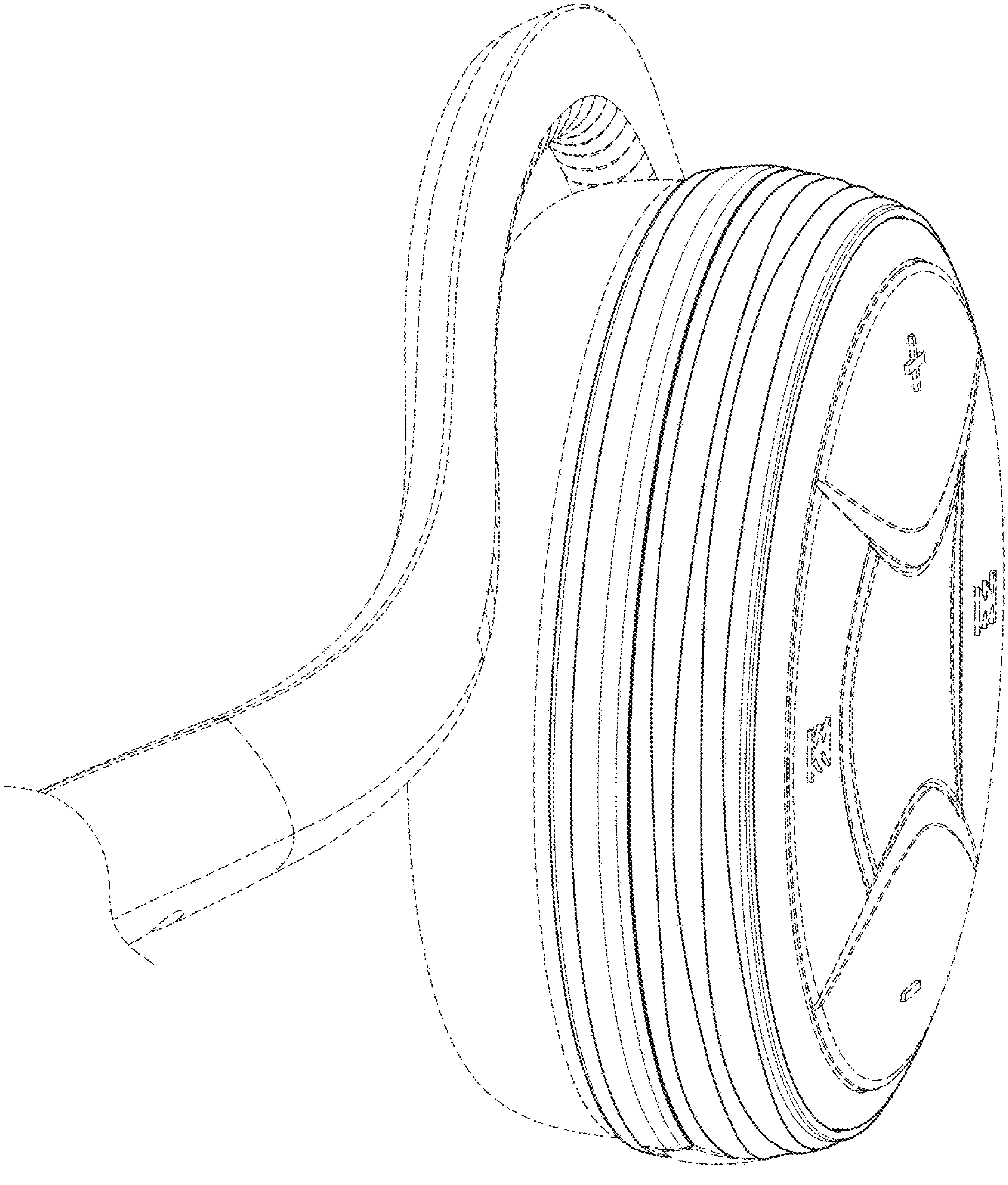


FIG. 7

FIG. 8



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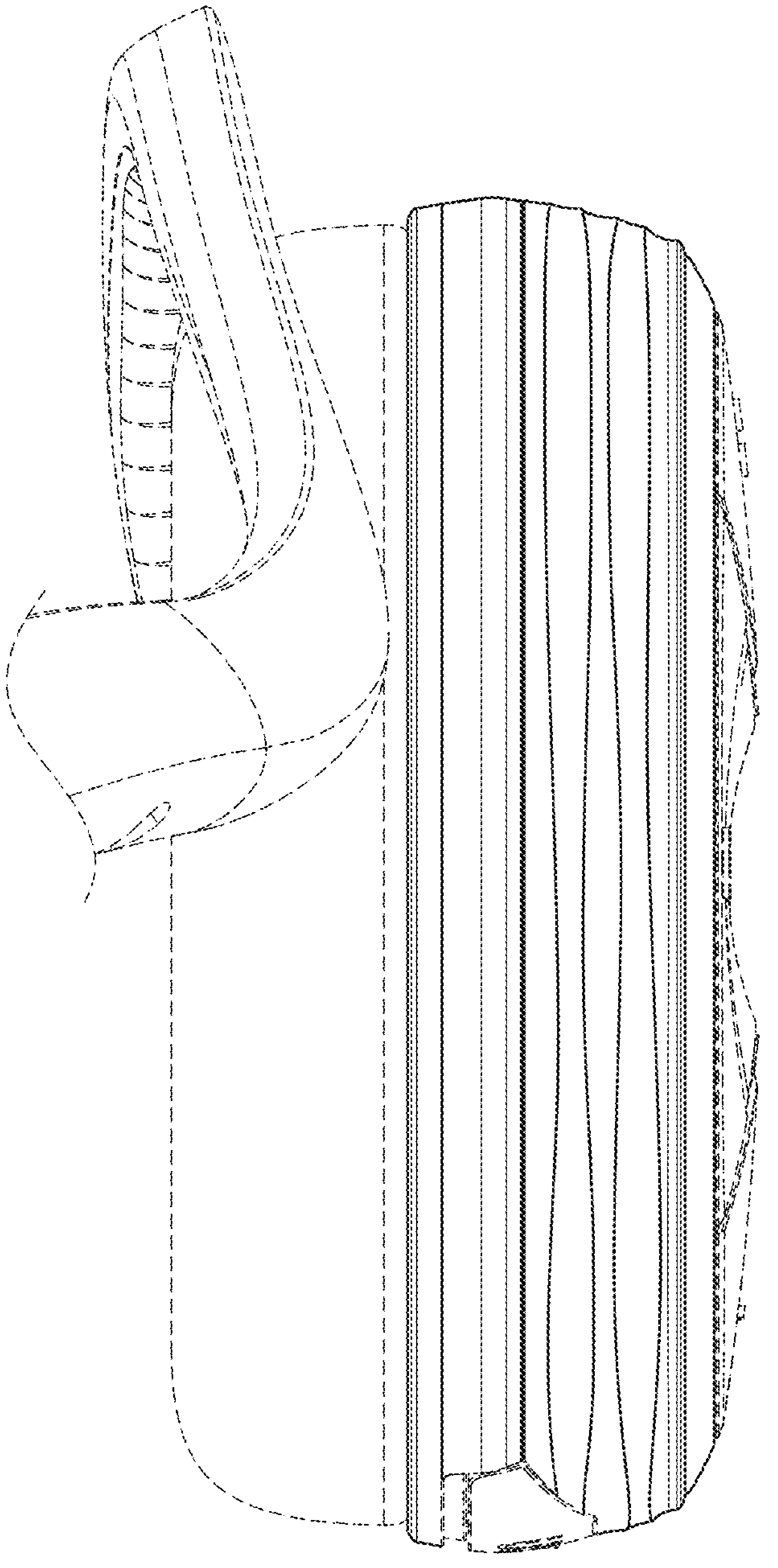
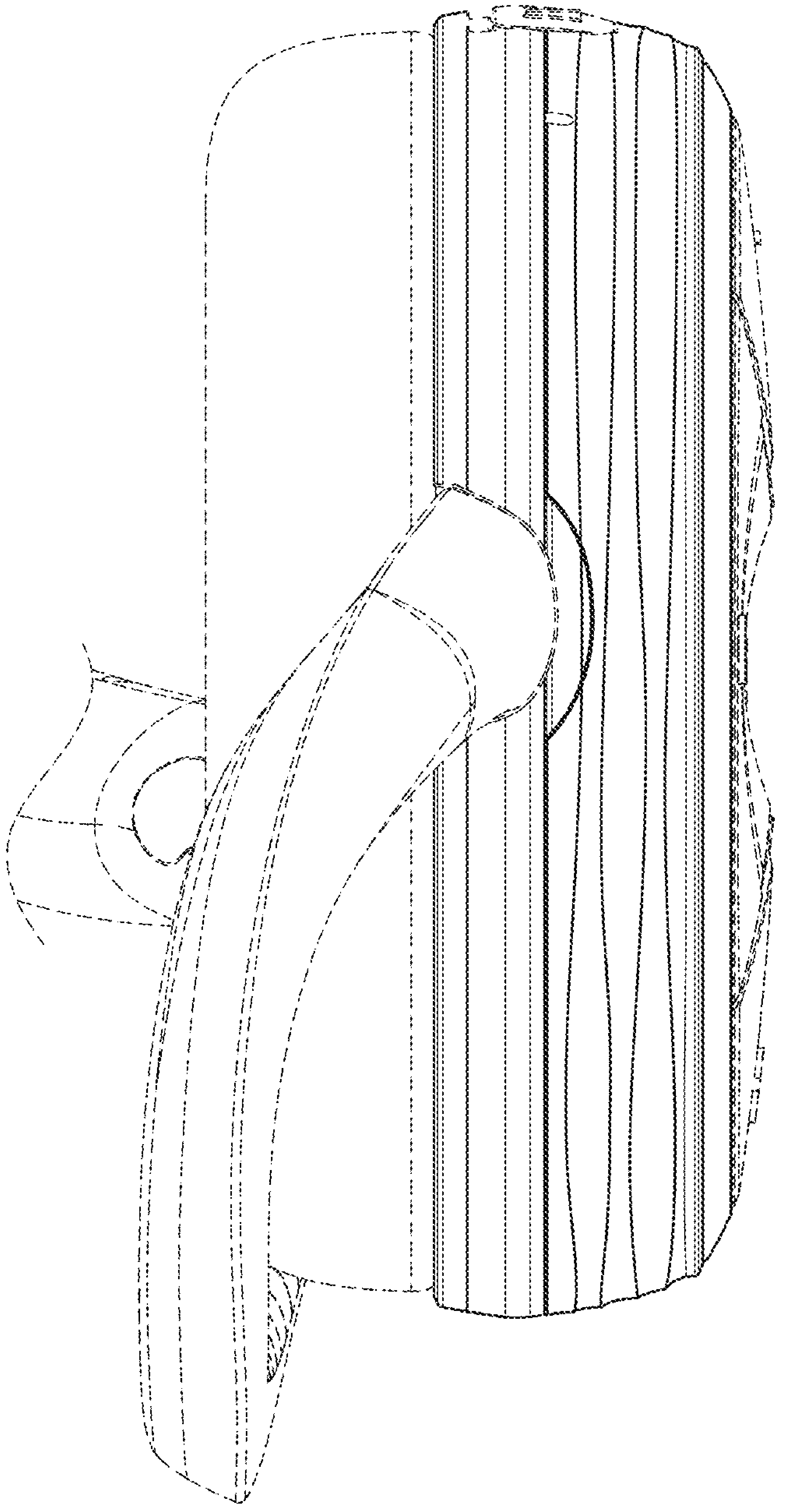


FIG. 10



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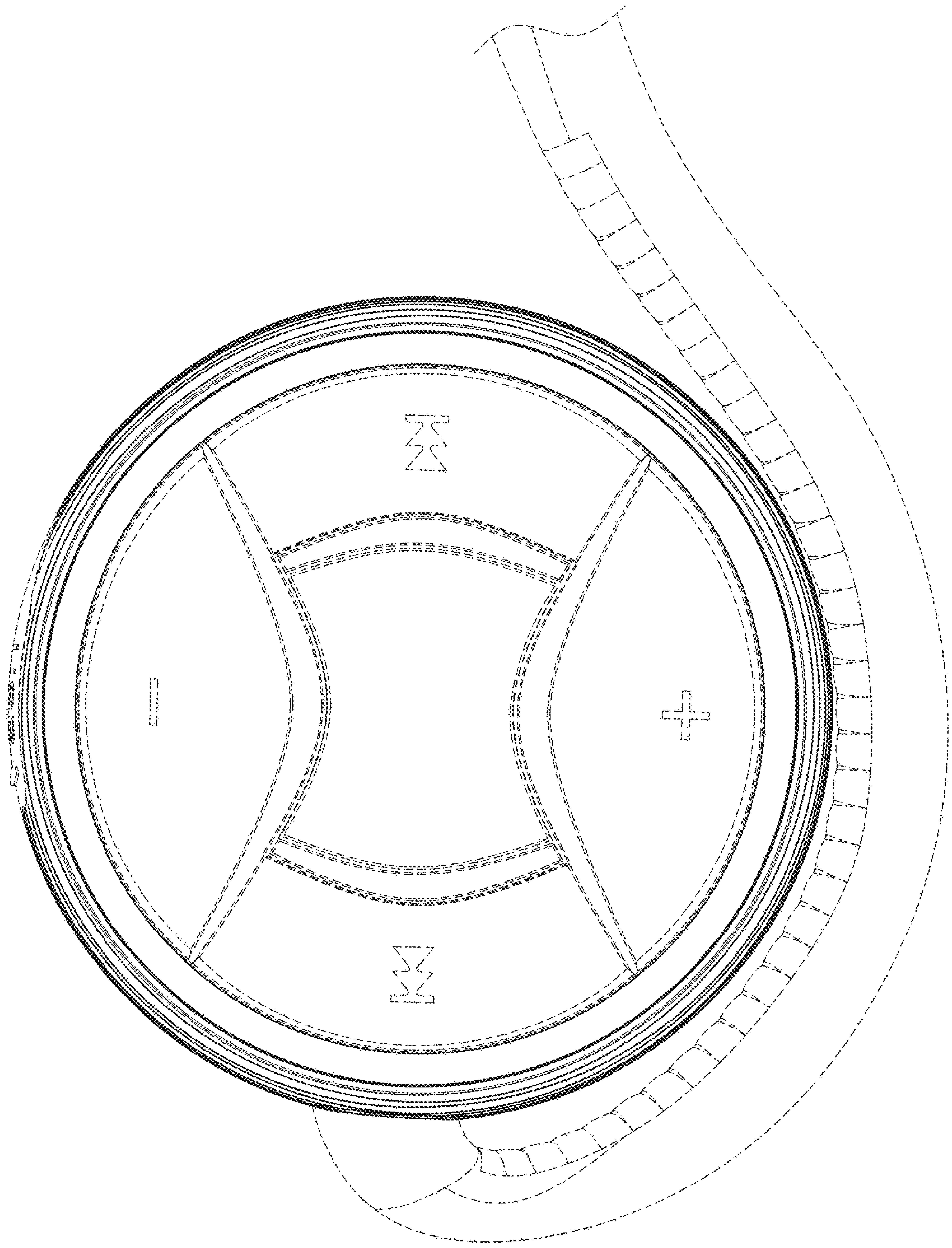

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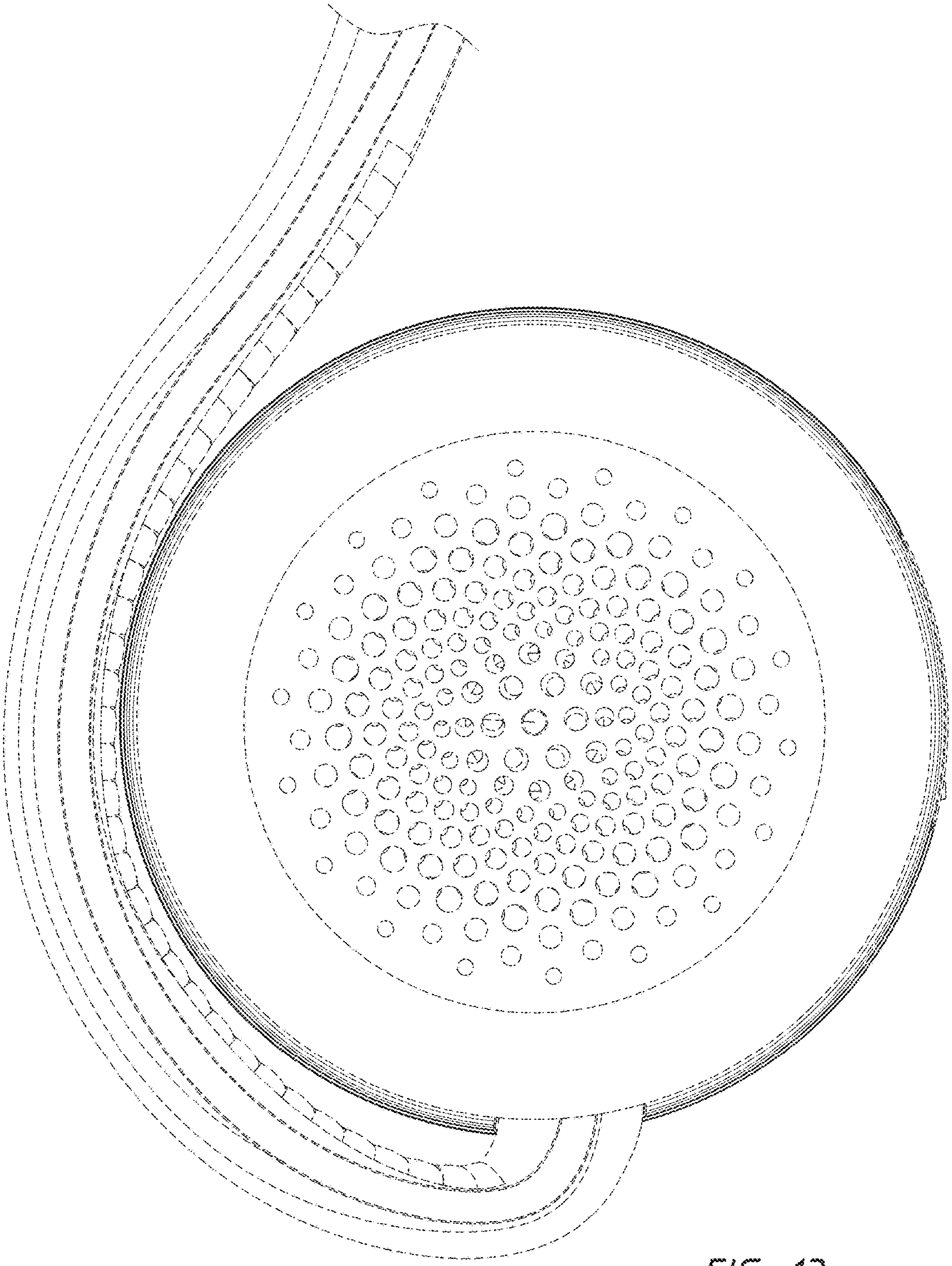

FIG. 13

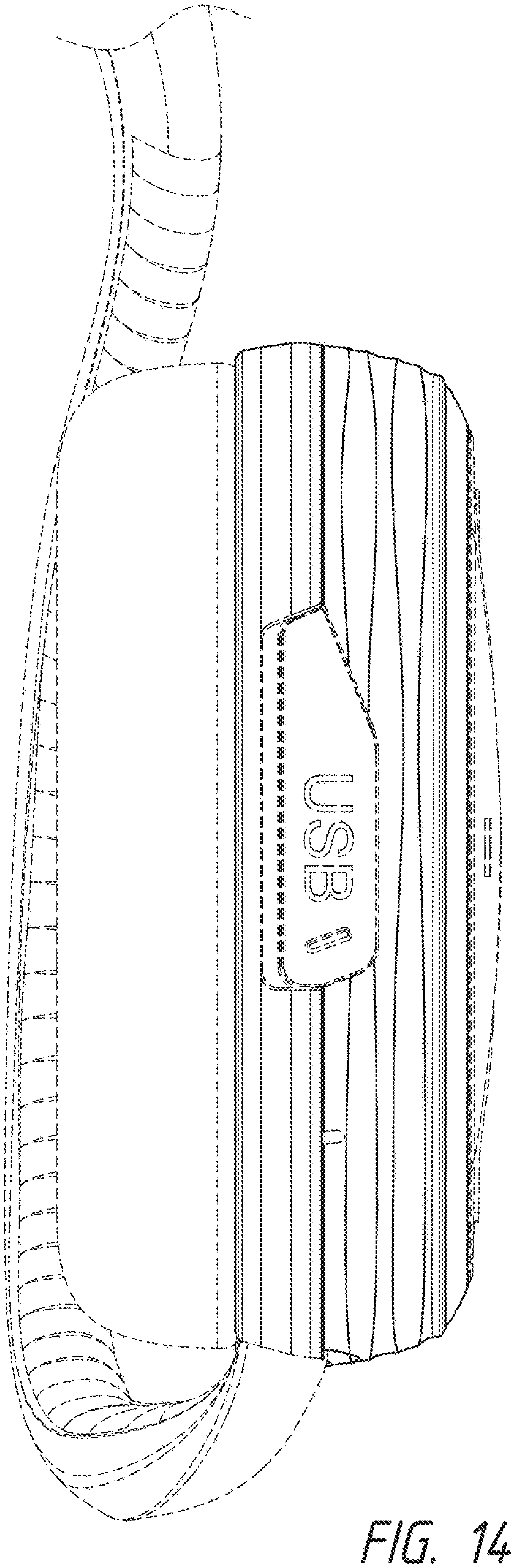

FIG. 14

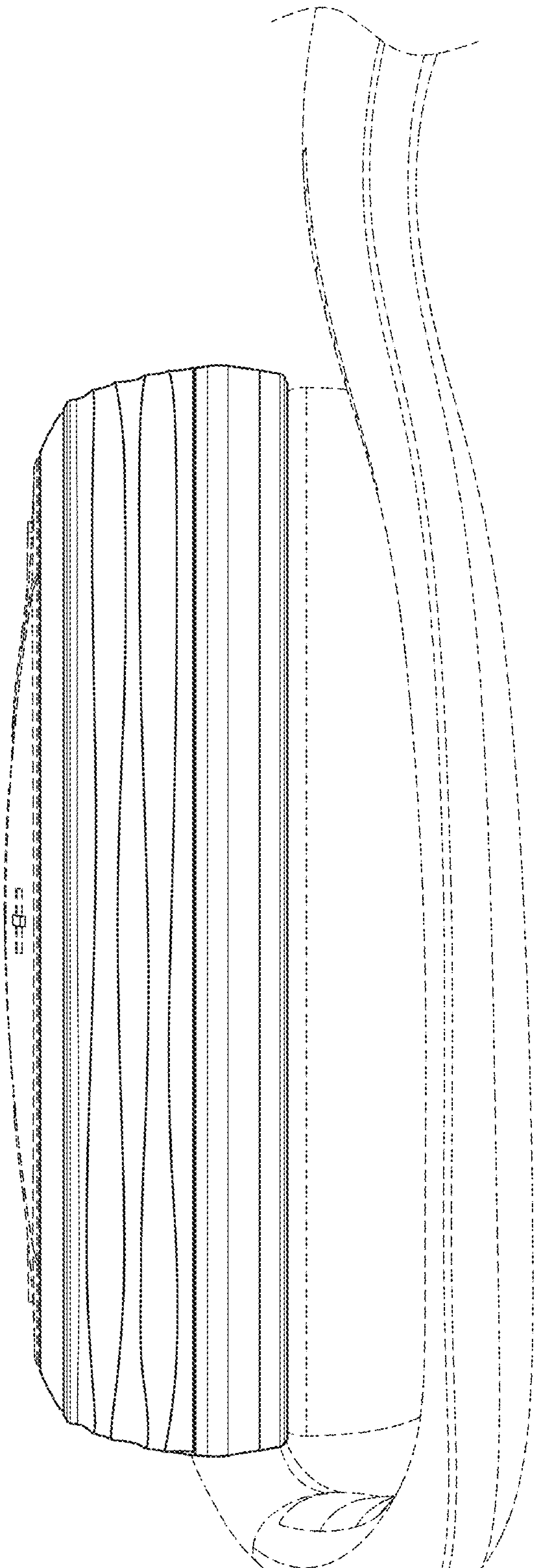

FIG. 15

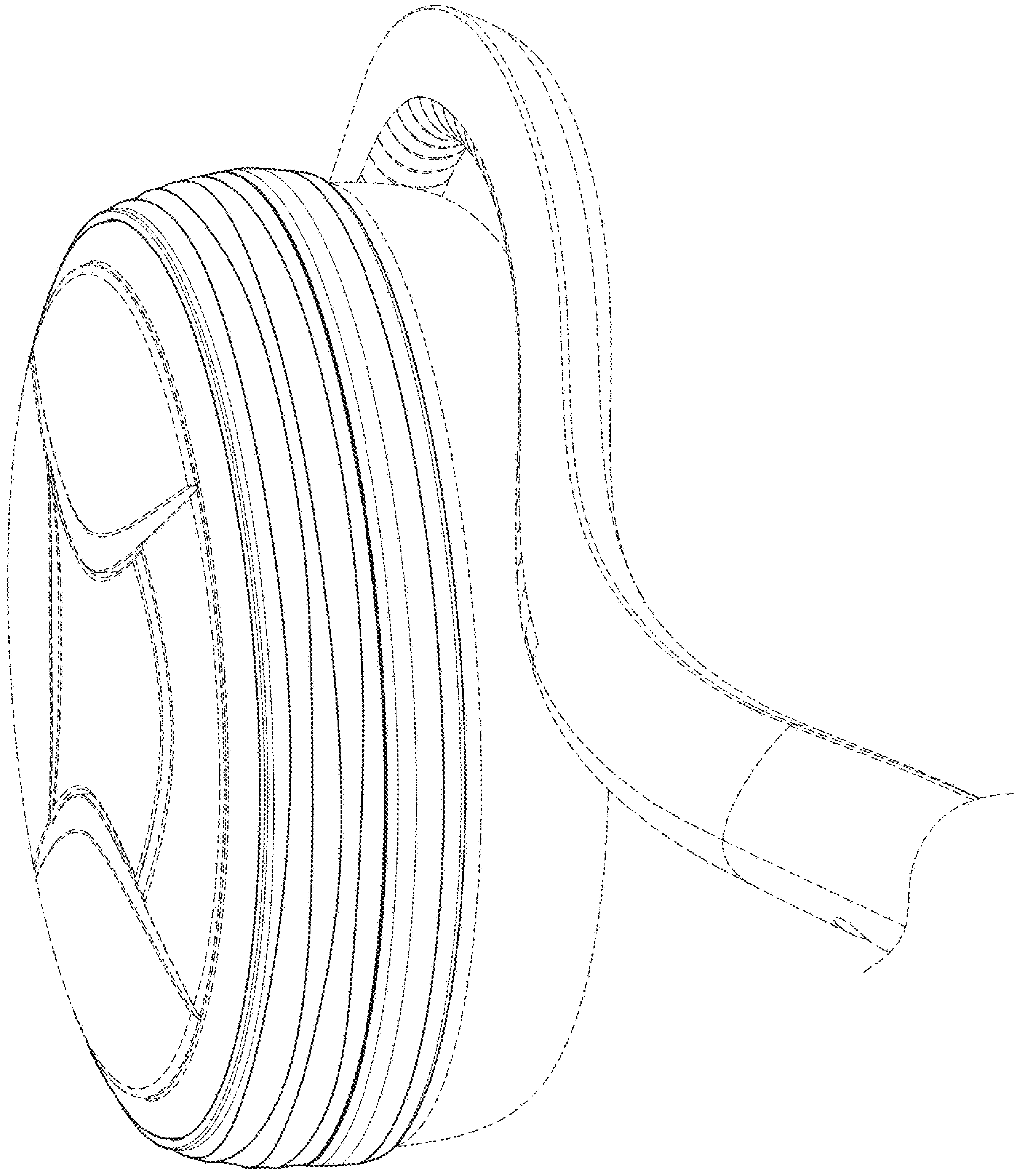

FIG. 16

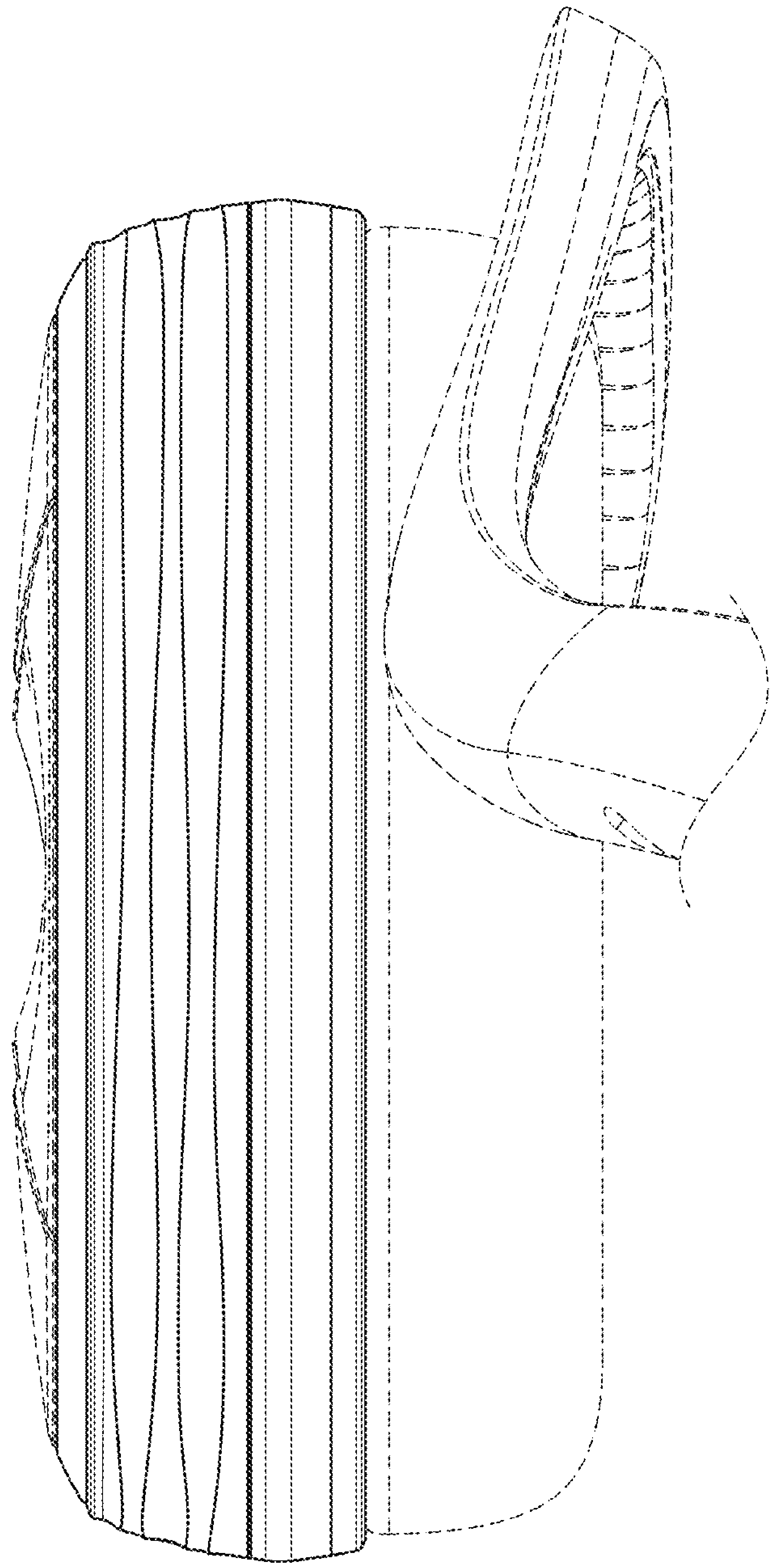

FIG. 17

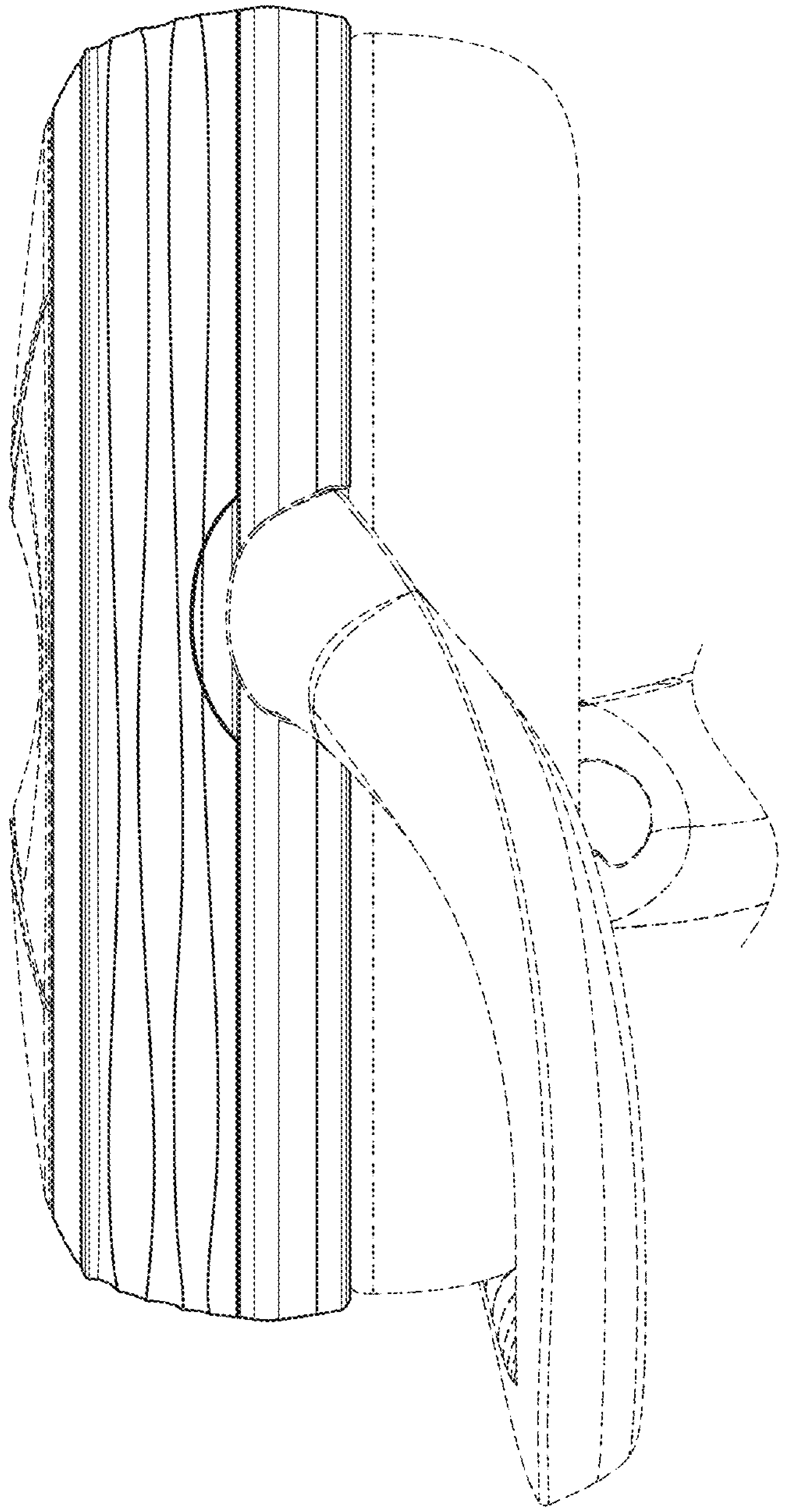

FIG. 18

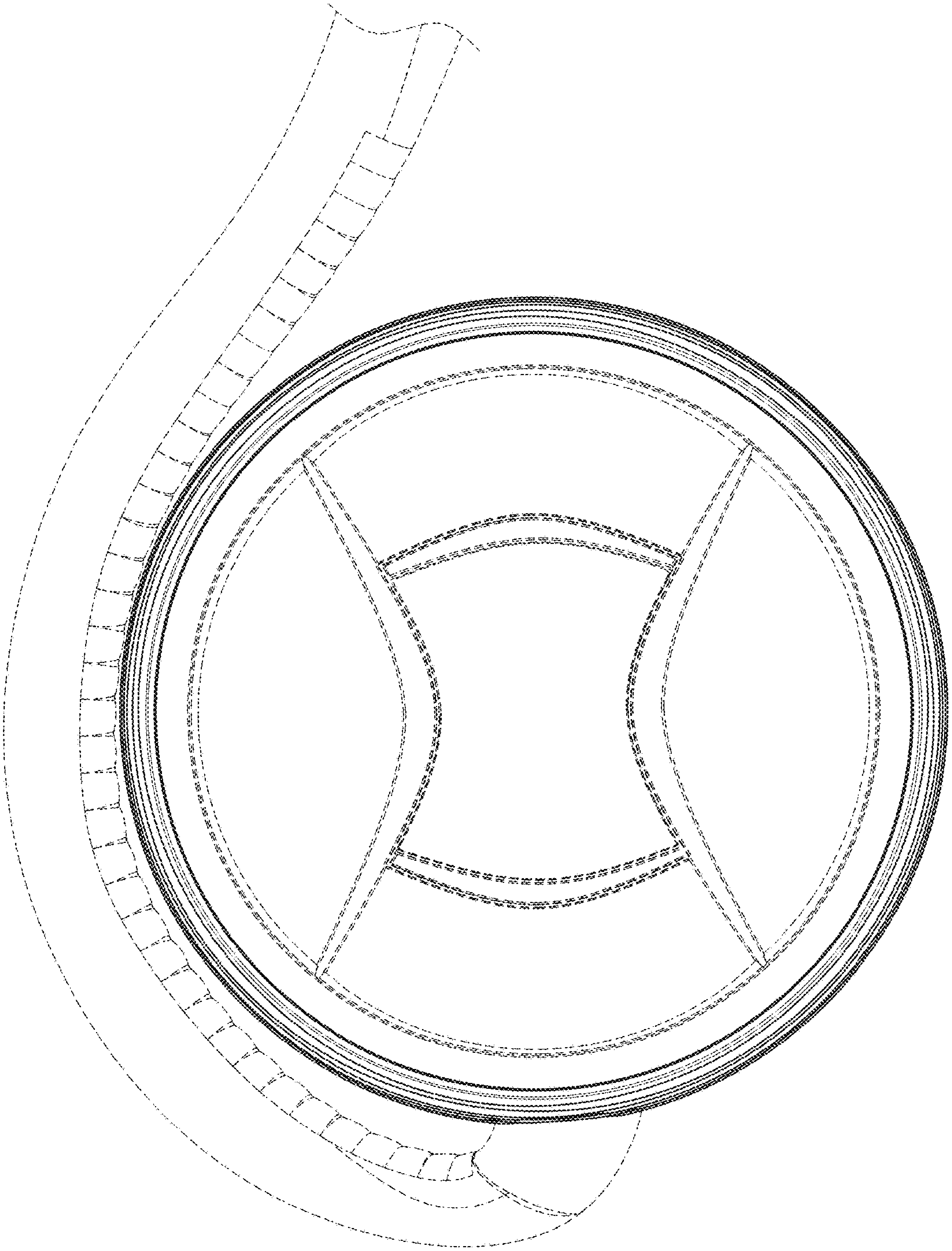

FIG. 19

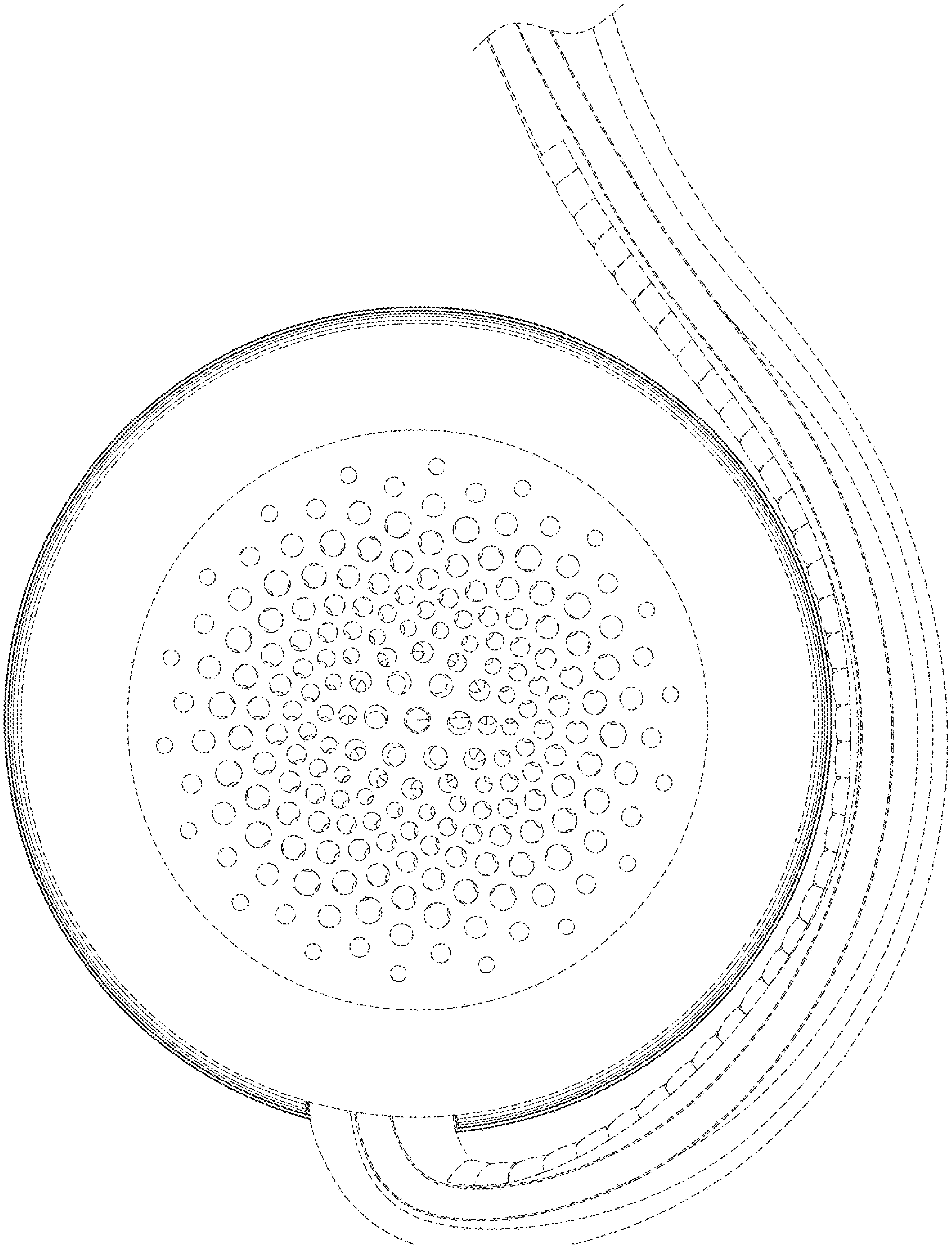

FIG. 20

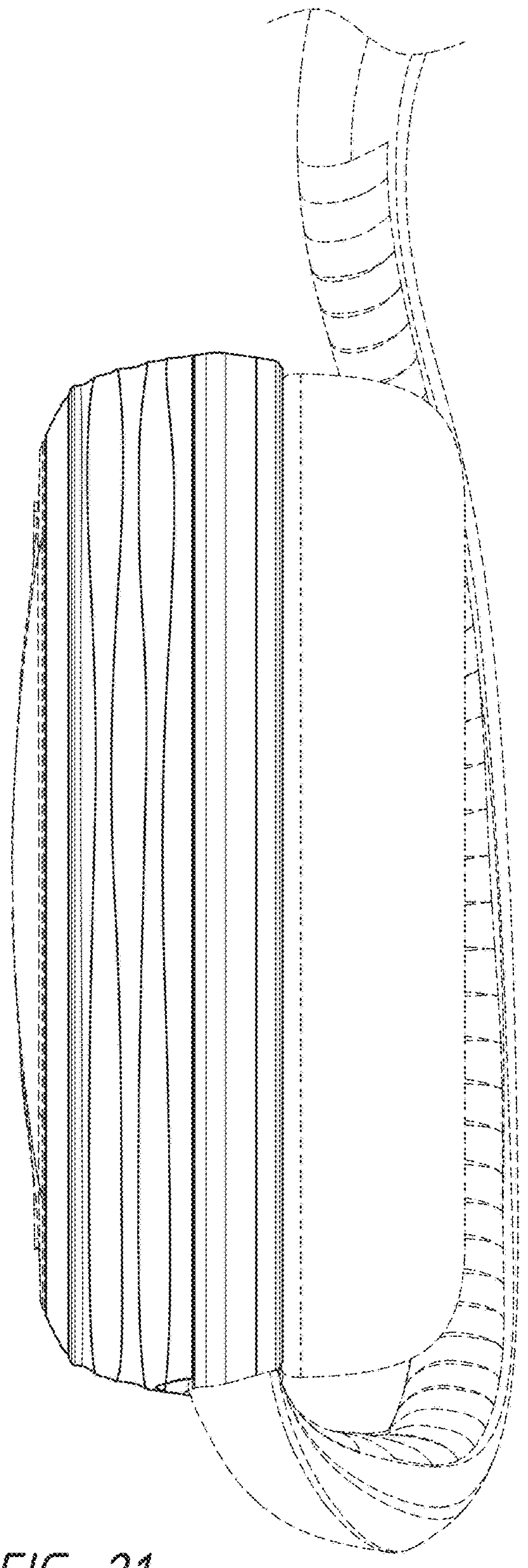

FIG. 21

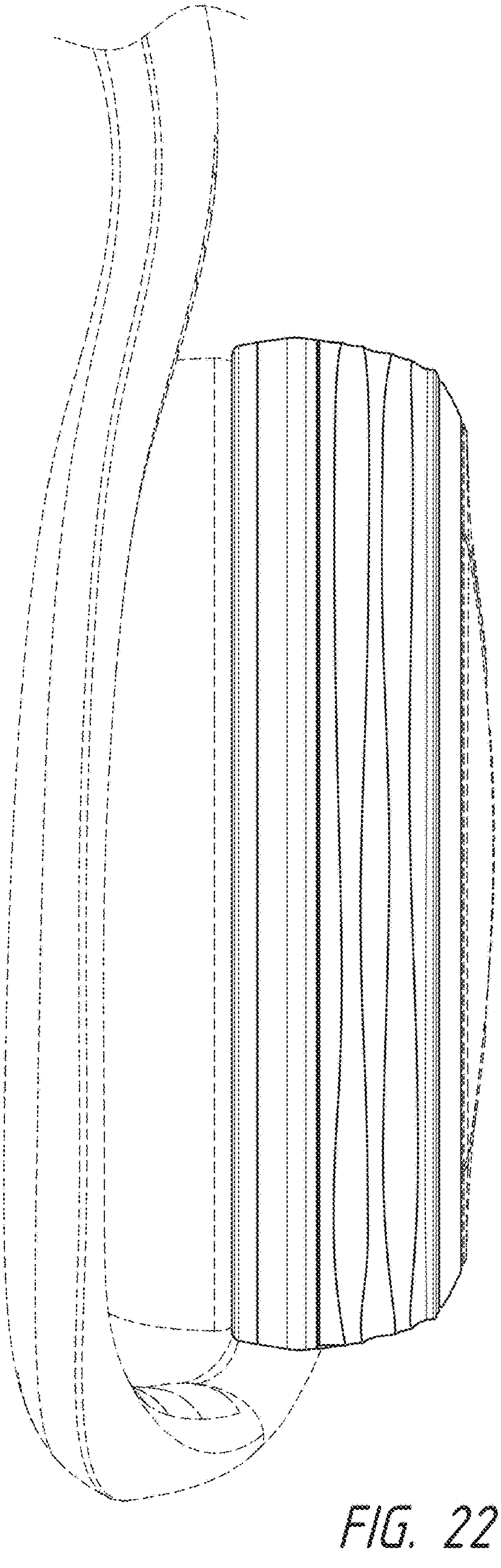

FIG. 22